

AMENDMENTS TO THE CLAIMS

Listing of the Claims:

Following is a listing of all claims in the present application, which listing supersedes all previously presented claims:

Claims 1-10. (Canceled)

11. (Currently Amended) An apparatus for exposing a peripheral area of a wafer, the apparatus comprising:

a wafer chuck on which a wafer formed with a photoresist film is loaded;

a first driving section operatively associated with the wafer chuck to drive the wafer chuck;

a light source for exposing a portion of the photoresist film formed on the wafer installed above the peripheral area of the wafer to generate a light;

an inspecting section for receiving light directly from the light source to inspect ~~inspecting~~ whether the light is precisely radiated from the light source onto the peripheral area of the wafer; and

a second driving section operatively associated with both the inspecting section and the light source for driving the light source to precisely radiate the light on the peripheral area of the wafer.

12. (Original) The apparatus as claimed in claim 11, wherein the first driving section comprises:

a rotating shaft supporting a lower portion of the wafer chuck and for rotating the wafer chuck;

a rail coupled to a lower portion of the rotating shaft that provides a route for driving the rotating shaft in a direction parallel to a flat zone of the wafer loaded on the wafer chuck; and

a moving section operatively associated with the rotating shaft for driving the wafer chuck along the route provided by the rail.

13. (Original) The apparatus as claimed in claim 11, wherein the light source is installed such that the light is radiated over the peripheral area of the wafer and an outer area beyond an edge portion of the wafer.

14. (Original) The apparatus as claimed in claim 11, wherein the inspecting section comprises:

a first detecting part installed remote from a rear surface of the peripheral area of the wafer to detect the light radiated toward an outer area beyond an edge portion of the wafer and to output an optical datum of the detected light;

a first determining part for receiving the optical datum from the first detecting part and comparing the optical datum with a reference optical datum to determine whether the optical datum is within a predetermined, allowable range of values; and

a first calculating part operatively associated with the first determining part for precisely calculating a position datum for the light source based on an error value of the optical datum received from the first determining part.

15. (Original) The apparatus as claimed in claim 14, wherein the first detecting part comprises:

a sensing part for sensing an intensity of radiation of the light radiated toward the outer area beyond an edge portion of the wafer; and

an outputting part for outputting the intensity of radiation of the light sensed by the sensing part.

16. (Original) The apparatus as claimed in claim 14, wherein the reference optical datum is an optical datum that is detected when the predetermined width of the peripheral area of the wafer is uniformly exposed to the light.

17. (Currently Amended) ~~The apparatus as claimed in claim 11, wherein the inspecting section comprises:~~

An apparatus for exposing a peripheral area of a wafer, the apparatus comprising:

a wafer chuck on which a wafer formed with a photoresist film is loaded;

a first driving section operatively associated with the wafer chuck to drive the wafer chuck;

a light source installed above the peripheral area of the wafer to generate a light;

an inspecting section for inspecting whether the light is precisely radiated from the light source onto the peripheral area of the wafer, the inspecting section including:

a second detecting part positioned horizontally remote from an edge portion of the wafer, which includes a portion to which the light is radiated, for detecting a distance between the edge portion of the wafer and a reference point positioned on an extension line extended from a center of the wafer beyond the edge portion of the wafer;

a second determining part for receiving a detected distance datum from the second detecting part and comparing the detected distance datum with a reference distance datum to determine whether the detected distance datum is within a predetermined, allowable range of values; and

a second calculating part operatively associated with the second determining part for precisely calculating a position of the light source and a position datum of the light source for radiating the light at the position based on an error value between the distance datum and the reference distance datum; and

a second driving section operatively associated with both the inspecting section and the light source for driving the light source to precisely radiate the light on the peripheral area of the wafer.

18. (Original) The apparatus as claimed in claim 17, wherein the reference distance datum is a distance between the edge portion of the wafer and the reference point that is detected when the predetermined width of the peripheral area of the wafer is uniformly exposed to the light.

19. (Original) The apparatus as claimed in claim 11, wherein the second driving section receives a position datum of the light source from the inspecting section and drives the light source in an inner or an outer direction of the wafer in response to the position datum.